



# DuPont™ Posistrip® EKC800™ Series

Photoresist Removers

For Positive Photoresist Removal

## Product Description

DuPont™ Posistrip® photoresist removers are organic blends specifically formulated to remove positive photoresist from substrate surfaces used in the microelectronics industry.

Formulated to meet a wide range of process requirements, Posistrip® products vary from mildly aggressive non-alkaline chemistries for removal of photoresist from sensitive metal layers or substrates like GaAs, to very aggressive alkaline chemistries for removal of extremely hardened photoresist. These water-rinsable formulations allow the user to complete the photoresist removal process with less chemistry and lower cost of ownership (CoO). These products are low in metal ions, non-corrosive to sensitive metals and contain no phenol or chlorinated solvents. Posistrip® products are compatible with automatic equipment allowing for easy conversion from manual wet station environments.

## DuPont™ Posistrip® EKC800™ Series photoresist removers include:

### Posistrip® EKC800™

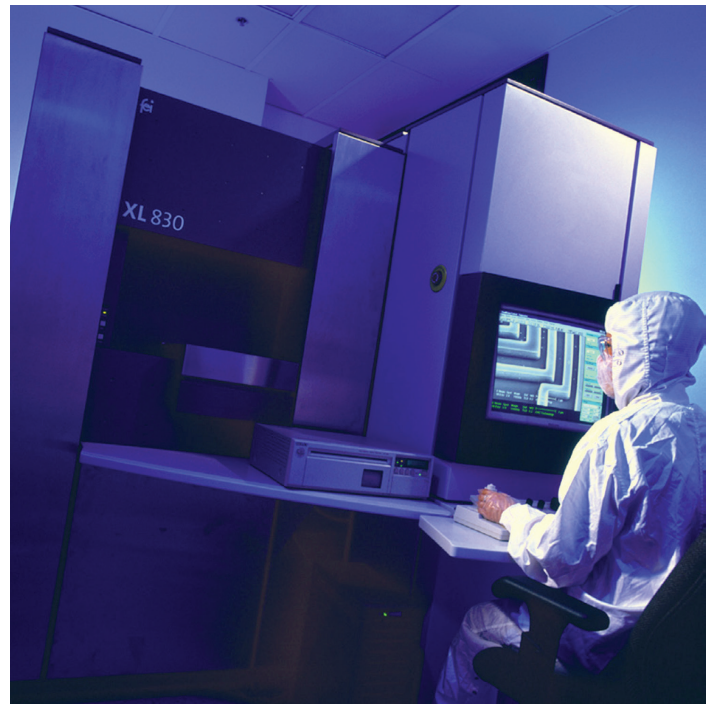
Designed to remove positive photoresist that has experienced standard processing with normal thermal history.

### Posistrip® EKC830™

Designed to effectively remove positive photoresist resulting from harsh prior processing that is difficult to remove.

### Posistrip® EKC865™

Specifically formulated to prevent attack of sensitive metals. Removes positive photoresist with normal thermal history.





[ekctech.dupont.com](http://ekctech.dupont.com)

For more information on DuPont™ Posistrip® EKC800™ or other DuPont products, please visit our website.

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**CAUTION:** Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

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